3.3V Dual LVTTL/LVCMOS to Differential LVPECL Translator

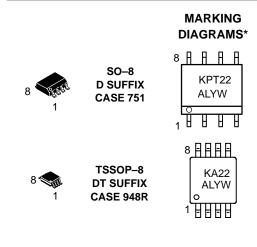
The MC100EPT22 is a dual LVTTL/LVCMOS to differential LVPECL translator. Because LVPECL (Positive ECL) levels are used only +3.3 V and ground are required. The small outline 8–lead package and the single gate of the EPT22 makes it ideal for those applications where space, performance, and low power are at a premium. Because the mature MOSAIC 5 process is used, low cost and high speed can be added to the list of features.

- 420 ps Typical Propagation Delay
- Maximum Frequency > 1.1 GHz Typical
- Operating Range: $V_{CC} = 3.0 \text{ V}$ to 3.6 V with GND = 0 V
- PNP LVTTL Inputs for Minimal Loading
- Q Output Will Default HIGH with Inputs Open
- The 100 Series Contains Temperature Compensation.



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A = Assembly Location L = Wafer Lot

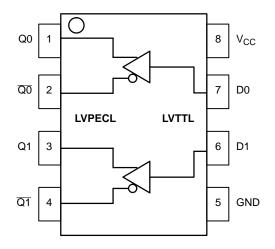
Y = Year

W = Work Week

*For additional information, see Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
MC100EPT22D	SO–8	98 Units/Rail
MC100EPT22DR2	SO–8	2500 Tape & Reel
MC100EPT22DT	TSSOP-8	100 Units/Rail
MC100EPT22DTR2	TSSOP-8	2500 Tape & Reel



PIN DESCRIPTION					
PIN	FUNCTION				
Q0, Q1, <u>Q0</u> , <u>Q1</u>	LVPECL Differential Outputs				
D0, D1	LVTTL Inputs				
V _{CC}	Positive Supply				
GND	Ground				

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

ATTRIBUTES

Characteris	Characteristics		
Internal Input Pulldown Resistor	N/A		
Internal Input Pullup Resistor		N/A	
ESD Protection	Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV	
Moisture Sensitivity, Indefinite Time C	Dut of Drypack (Note 1.)	Level 1	
Flammability Rating Oxygen Index		UL-94 code V-0 A 1/8" 28 to 34	
Transistor Count		164 Devices	
Meets or exceeds JEDEC Spec EIA/	JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS (Note 2.)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	Power Supply	GND = 0 V		6	V
VI	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
ТА	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θJC	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

2. Maximum Ratings are those values beyond which device damage may occur.

TTL INPUT DC CHARACTERISTICS V_{CC}= 3.3 V, GND= 0.0 V, T_A= -40° C to 85° C

Symbol Characteristic		Condition	Min	Тур	Max	Unit
I _{IH}	Input HIGH Current	V _{IN} = 2.7 V			20	μA
I _{IHH}	Input HIGH Current MAX	V _{IN} = 6.0 V			100	μA
IIL	Input LOW Current	V _{IN} = 0.5 V			-0.6	mA
V _{IK}	Input Clamp Voltage	I _{IN} = -18 mA			-1.0	V
V _{IH}	Input HIGH Voltage		20			V
V _{IL}	Input LOW Voltage				0.8	V

PECL OUTPUT DC CHARACTERISTICS V_{CC} = 3.3 V, GND = 0.0 V (Note 3.)

		–40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	Input HIGH Voltage (Single Ended)	32	43	55	35	45	60	37	46	62	mA
V _{OH}	Input LOW Voltage (Single Ended) (Note 4.)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Input HIGH Current (Note 4.)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

3. Output parameters vary 1:1 with V_{CC} .

4. All loading with 50 ohms to V_{CC}-2.0 V.

AC CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, GND= 0.0 V (Note 5.)

		−40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (See Figure 2. F _{max} /JITTER)	0.8	1.1		0.8	1.1		0.8	1.1		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential	250	400	650	250	420	675	300	500	700	ps
t _{JITTER}	Cycle–to–Cycle Jitter (See Figure 2. F _{max} /JITTER)		0.2	< 1		0.2	< 1		0.2	< 1	ps
t _r t _f	Output Rise/Fall Times $(20\% - 80\%)$ Q, \overline{Q}	50	110	200	60	120	220	70	140	250	ps

5. Measured using a 2.4 V source, 50% duty cycle clock source. All loading with 50 ohms to V_{CC} -2.0 V.

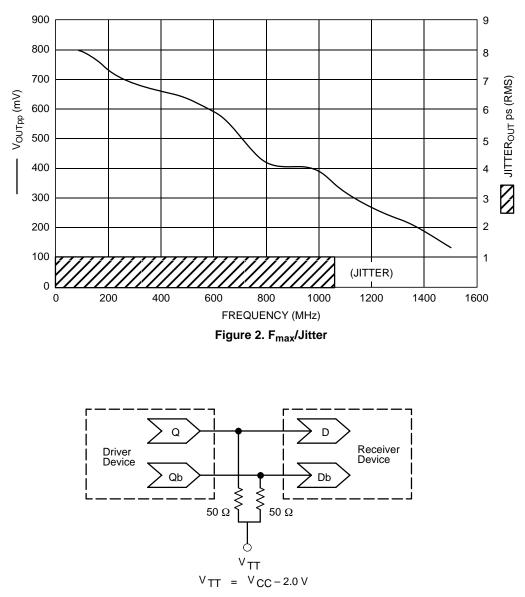


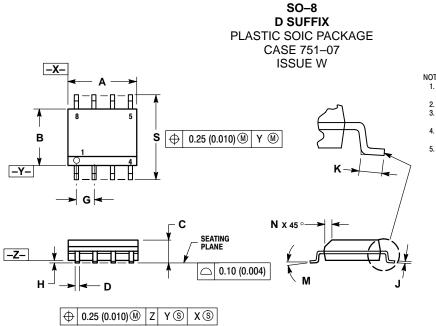
Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020 – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

- AN1404 - ECLinPS Circuit Performance at Non-Standard VIH Levels AN1405 - ECL Clock Distribution Techniques AN1406 Designing with PECL (ECL at +5.0 V) AN1503 - ECLinPS I/O SPICE Modeling Kit AN1504 Metastability and the ECLinPS Family AN1560 - Low Voltage ECLinPS SPICE Modeling Kit AN1568 Interfacing Between LVDS and ECL AN1596 - ECLinPS Lite Translator ELT Family SPICE I/O Model Kit AN1650 - Using Wire-OR Ties in ECLinPS Designs AN1672 - The ECL Translator Guide AND8001 Odd Number Counters Design
- AND8002 Marking and Date Codes
- AND8020 Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at http://onsemi.com.

PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI

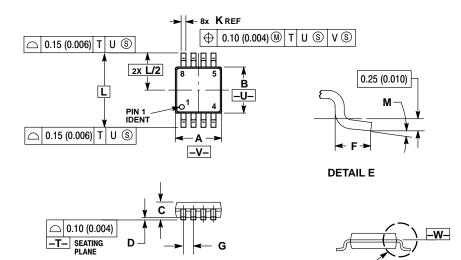
Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. DIMENSION A AND B DO NOT INCLUDE MOLD

- PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER 4.
- SIDE.

SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES		
DIM	M MIN MAX		MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
Μ	0 °	8 °	0 °	8 °		
Ν	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) 4.
- PER SIDE. TERMINAL NUMBERS ARE SHOWN FOR 5.

REFERENCE ONLY.
DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	2.90 3.10		0.114	0.122	
В	2.90	2.90 3.10		0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40 0.70		0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25 0.40		0.010	0.016	
L	4.90 BSC		0.193 BSC		
Μ	0° 6°		0°	6 °	

DETAIL E

<u>Notes</u>

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